

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	9940759
<b>Application Number:</b>	10561299
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	3881
<b>Title of Invention:</b>	Integrated circuit on high performance chip
<b>First Named Inventor/Applicant Name:</b>	Jean-Pierre Joly
<b>Customer Number:</b>	90678
<b>Filer:</b>	Jasper W. Dockrey/Maggie Pieczonka
<b>Filer Authorized By:</b>	Jasper W. Dockrey
<b>Attorney Docket Number:</b>	9905/34 (BIF023273US)
<b>Receipt Date:</b>	26-APR-2011
<b>Filing Date:</b>	15-DEC-2005
<b>Time Stamp:</b>	12:14:18
<b>Application Type:</b>	U.S. National Stage under 35 USC 371

### Payment information:

Submitted with Payment	no
------------------------	----

### File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	NPL Documents	Blanchard-Lagahae-C-Hydrogen-and-Helium.pdf	584601 9cf85b3fb428fdb71013f5d2fb08c1969e8d7f31	no	13

### Warnings:

### Information:

2	NPL Documents	Blochl_P_et_al.pdf	290290	no	4
			4a7bf7851fdc2e5036bb42945bbd513b3a47a80d		
Warnings:					
Information:					
3	NPL Documents	Borgatti_Stephen_The_Root-Mean_Square.pdf	44565	no	1
			6d4d4ea68fe95650a77d85a157564d7468f48b77		
Warnings:					
Information:					
4	NPL Documents	Bruel_et_al_1997_1636-1641.pdf	374214	no	6
			a42c89798c1c4a78ade3c5c4b5dc5714379a721f		
Warnings:					
Information:					
5	NPL Documents	Bruel_M_et_al_Vol_99-1_Meeting_Abstract.pdf	127811	no	2
			37ed322e0f2852c05a24cb4c307e3d844cd4e956		
Warnings:					
Information:					
6	NPL Documents	Bruel_M_Silicon_on_Insulator_Material.pdf	118402	no	2
			025dbd7c641340f1791e85affcb46172fd05d97a		
Warnings:					
Information:					
7	NPL Documents	Bruel_M_Silicon_on_insulator_material_technology.pdf	123231	no	2
			0961cf5fbedc1dfdc1e7f28a8e99942f1319be4b		
Warnings:					
Information:					
8	NPL Documents	Bruel_M_Smart_Cut_A_New_SOI_Material_Technology.pdf	2170085	no	25
			2bf0c4b136c26aba8c7e76750a973afb47e5bb5e		
Warnings:					
Information:					
9	NPL Documents	Bruel_M_Smart_Cut_A_Promising_New_SOI.pdf	122154	no	2
			f472cec49b125e55a79c939240a763c1fad76d0		
Warnings:					
Information:					
10	NPL Documents	Bruel_M_Smart_Cut_Process.pdf	2566926	no	26
			727a664329ca8a20cefa8ce60dc6fe11219bfff54		
Warnings:					
Information:					

11	NPL Documents	Bruel_Michel_Application_of_Hydrogen_on_Beams_to_Silicon.pdf	483916	no	7
			dd5290d8cc824ccc32f867cd44748958e663db3d		
Warnings:					
Information:					
12	NPL Documents	Camperi-Ginestet_et_al_Alignable_Epitaxial_Liftoff.pdf	312927	no	4
			fd8761331bd75d5fb848e66373d1ac2752cc37aa7		
Warnings:					
Information:					
13	NPL Documents	Canham_et_al.pdf	217996	no	5
			ea035ddece42c428b2e02a79ff04309294432f08		
Warnings:					
Information:					
14	NPL Documents	Carter_et_al_107-114.pdf	669972	no	8
			318947f8496c9a661b960b5823aafa38615b5408		
Warnings:					
Information:					
15	NPL Documents	Carter-et-al_30-36.PDF	600857	no	13
			2313c4539fcc7c3808380d3dfcbcb24b7d2abfc2		
Warnings:					
Information:					
16	NPL Documents	Cassidy.pdf	195180	no	3
			44bea92241c0a3fffd4a7f1bf296b83432081b76e		
Warnings:					
Information:					
17	NPL Documents	Cerofolini_et_al_1992.pdf	674531	no	10
			bafe56a2af65df52e444896283305b5a55add363		
Warnings:					
Information:					
18	NPL Documents	Cerofolini_et_al_2000_1-52.PDF	2728185	no	52
			d2d59f31dbf822830d9b030bf999539d0dbc98ad		
Warnings:					
Information:					
19	NPL Documents	Cerofolini_et_al_2000_196-202.pdf	510141	no	7
			f702e35a9a8a7ef362d9be0de6bd7e7c64894c5a		
Warnings:					
Information:					

20	NPL Documents	Chu_Ion_Implantation_In_Semiconductors.PDF	499300	no	12
			9988f6882ac689449d57f10540047e8f65595bec		
Warnings:					
Information:					
21	NPL Documents	Chu_PK_Plasma_Immersion_Ion_Implantation.pdf	245084	no	5
			80a176350a73b27358abab9848eb795e24ee2797		
Warnings:					
Information:					
22	NPL Documents	Chu_WK_et_al_Radiation_Damage_of_50-250_keV_Hydrogen.pdf	663443	no	10
			5f5f7f6c209a80cdc60eb9bea796910ad3d19a15		
Warnings:					
Information:					
23	NPL Documents	Cowen_N_et_al.pdf	499500	no	8
			83cda760dd7229f1c1106d7f4dfd9a2a89a2e5b6		
Warnings:					
Information:					
24	NPL Documents	Cristoloveanu_S_et_al_Electrical_Properties_of_Unibond.pdf	157840	no	3
			94d81140d574e1901ec303421ff5004a0ed324f7		
Warnings:					
Information:					
25	NPL Documents	Csepregi_L_et_al.pdf	125356	no	2
			c7c7838dc2491111cb474f58ec21aee6dd1a2533		
Warnings:					
Information:					
26	NPL Documents	Cullis_AG_et_al.pdf	660281	no	11
			2fe7d146fd1226168532140298ced0dddfefafa38		
Warnings:					
Information:					
27	NPL Documents	Demeester_et_al.pdf	1057147	no	13
			e514a67ef257a1b59cd7bd60d39af05986a40b7c		
Warnings:					
Information:					
28	NPL Documents	Denteneer_et_al_1989_979-984.pdf	299205	no	5
			9a4be7616268e450c107930a24c1956759a6b8ba		
Warnings:					
Information:					

29	NPL Documents	Denteneer_et_al_April_1989.pdf	342276	no	4
			a91ff56edf7086aa9e74cdcafb2827aa5ee12a8a		
Warnings:					
Information:					
30	NPL Documents	DiCioccio_et_al_1997_349-356.pdf	744238	no	8
			d8d8d2811871ed7fd4fbee1e5e0a562659640bad		
Warnings:					
Information:					
31	NPL Documents	DiCioccio_et_al_1996_1144-1145.pdf	130526	no	2
			f3f564678f1bb826e45d975574c99b2989092ac4		
Warnings:					
Information:					
32	NPL Documents	Diem_et_al.pdf	846924	no	10
			149415ab87fed2d9ed8105d2a9ac0e832d9998ca		
Warnings:					
Information:					
33	NPL Documents	Dirks_et_al.pdf	1187199	no	15
			6b089b5565b3cbe5389aaa781ca71cc23e78fc0		
Warnings:					
Information:					
34	NPL Documents	Duo_et_al_Comparison_Between_The_Different.pdf	821079	no	6
			6519e4d26a98aed37e9d54f06b517ddaab7ea02d		
Warnings:					
Information:					
35	NPL Documents	Duo-et-al-Evolution-of-Hydrogen-and-Helium_1.PDF	549396	no	6
			0e37d771df074bcd56fba107f0f36ae063f281a		
Warnings:					
Information:					
36	NPL Documents	Eaglesham_White_et_al_Equilibrium_Shape_of_Si.pdf	272298	no	4
			5602f2e891fcd72813254578fcd7de7e3d22897b		
Warnings:					
Information:					
37	NPL Documents	EerNisse_E-Compaction_of_Ion-Implanted_Fused_Silica.pdf	768866	no	8
			8a4542aa7694733b33057fc7d297c153ff17f1c2		
Warnings:					
Information:					

38	NPL Documents	EerNisse_EP- Role_of_Integrated_Lateral_ Str ess_In_Surface.pdf	801341 c1c625f6e6ad75561111b6a2253dc5f79cd41a70	no	9
<b>Warnings:</b>					
<b>Information:</b>					
39	NPL Documents	Evans_JH_An_Interbubble_Fra cture_Mechanism_Of_Blister. pdf	869679 da7e36616b7161668c796ee119344efcd6789bb	no	12
<b>Warnings:</b>					
<b>Information:</b>					
40	NPL Documents	Feijoo_et_al- Prestressing_of_Bonded.pdf	390788 6e4546b0647157aca4b2ed11123fd63bbeb1fd43	no	9
<b>Warnings:</b>					
<b>Information:</b>					
41	NPL Documents	Feng_et_al.pdf	137308 7b69fb79763717ee52a4a8a8e9bfb851b2905415	no	3
<b>Warnings:</b>					
<b>Information:</b>					
42	NPL Documents	Fukitsuka_et_al.pdf	488514 e2bb2ae358900fb91e7437c53471d27ea790dff64	no	4
<b>Warnings:</b>					
<b>Information:</b>					
43	NPL Documents	Garnier.pdf	376649 3ab2d6c6d9647a91290089da18080db2635f5024	no	6
<b>Warnings:</b>					
<b>Information:</b>					
44	NPL Documents	Gerasimenko.pdf	423407 0ba07b0abd376be9dc6753daab01e32fe3c2edc2	no	7
<b>Warnings:</b>					
<b>Information:</b>					
45	NPL Documents	Ghandi.pdf	145184 deb5206b7d6a70e5146e8c11fa0ff801416e7917	no	4
<b>Warnings:</b>					
<b>Information:</b>					
46	NPL Documents	Goesele_et_al_Semiconductor _Wafer_Bonding.pdf	1371808 2cd89afcb7bd07e55584a053137cf0c2e0527bad	no	28
<b>Warnings:</b>					
<b>Information:</b>					

47	NPL Documents	Greenwald_et_al.pdf	364299	no	4
			284ac2ea755b2373605663f3312b5af2416d0aa		
Warnings:					
Information:					
48	NPL Documents	Grovenor_C_Microelectronic_Materials.pdf	183072	no	5
			d4bd9c4d295257fbd1e504f92e143fc307942099		
Warnings:					
Information:					
49	NPL Documents	Guilhalmenc_C_et_al.pdf	266316	no	4
			de8b968045badcb478006f2b74b1b3bbdba55eb3		
Warnings:					
Information:					
50	NPL Documents	Hamaguchi_et_al_688-691.pdf	308961	no	4
			bd2819f285b888256918579a21f3095a1058db8f		
Warnings:					
Information:					
51	NPL Documents	Hamaguchi_et_al_Device_Layer_Transfer_Technique.pdf	157984	no	3
			ef26f17472e6db1c245cd8d154a67fb605e5a1ba		
Warnings:					
Information:					
52	NPL Documents	Henttinen_et_al-Mechanically_Induced_Si_Layer.pdf	248942	no	3
			084a59899bac7d2b8d9a6613752add4294e93ae3		
Warnings:					
Information:					
53	NPL Documents	Huang_et_al.pdf	77104	no	3
			6c21652aec420061641cfffdd641284e404a24e57		
Warnings:					
Information:					
54	NPL Documents	Hulett_DM_et_al_Ion_Nitriding_and_Ion_Impantation.pdf	228302	no	4
			f894673d4381b7976ede884eb3589dad03934092		
Warnings:					
Information:					
55	NPL Documents	IBM_August.pdf	31620	no	1
			6d441e872faf56aea6a339eab8aac6aeca66176c		
Warnings:					
Information:					

56	NPL Documents	IBM_July_1996.PDF	135377	no	5
			a0bd769b824620685b9bdf1738e37b02fd4db8a1		
Warnings:					
Information:					
57	NPL Documents	Jalaguier_1998_408-409.pdf	459112	no	2
			bbae93ad74a30deb946a886ae51b31a186f3fef3		
Warnings:					
Information:					
58	NPL Documents	Jalaguier_et_al_1999_26-27.pdf	204439	no	2
			0fe7aa5e31e34d5b0df44a2a3a163fbb57c3d658		
Warnings:					
Information:					
59	NPL Documents	Jaussaud_C_et_al.pdf	393224	no	3
			fbcf5ae0b610d798f76fcd6338055485e0fe4e11		
Warnings:					
Information:					
60	NPL Documents	Johnson.pdf	837642	no	9
			4618f06ca21720f7eb3f97a2d5d022d69f6ef47f		
Warnings:					
Information:					
Total Files Size (in bytes):			31687014		

**This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.**

**New Applications Under 35 U.S.C. 111**

**If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.**

**National Stage of an International Application under 35 U.S.C. 371**

**If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.**

**New International Application Filed with the USPTO as a Receiving Office**

**If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.**